



#13/Amend
4.26.02
CW
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Shunichi SEKI, et al.

Group Art Unit: 2814

Application No.: 09/423,969

Examiner: A. Mai

Filed: November 17, 1999

Docket No.: 104741

For: THIN FILM PATTERNING SUBSTRATE
AND SURFACE TREATMENT THEREFOR

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AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed January 14, 2002, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1-13, 15-24, 26, 28-47, 49-68 and 70-80 as follows.

1. (Amended) A thin film patterning substrate, used for forming thin films into patterns by an ink jet method, comprising:
- a surface whereof are formed banks and areas to be coated, partitioned by said banks;
- said banks having a width a (μm), a height thereof is made c (μm), a width of said areas to be coated is made b (μm), and an ink jet liquid droplet diameter of liquid material forming the thin film is made d (μm), said bank is formed so as to satisfy a relationship $d/2 < b < 5d$.